

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method for ~~producing~~ forming a film on a substrate, comprising:

~~discharging from an ink jet device onto a surface a composition, the composition comprising a liquid material from a nozzle of a head to the substrate to form a film on the substrate, the liquid material including a solvent and a solute, the solvent including at least one a heterocyclic compound, the heterocyclic compound having a furan skeleton, and a functional material selected from the group consisting of conductive materials, insulative materials and semiconductive materials, the at least one heterocyclic compound having one or more substituents excluding a hydrogen atom, containing an oxygen atom as a constituent group, and having a boiling point equal to or of the heterocyclic compound being greater than 170°C, and the solvent including a benzene derivative; and~~
~~removing the solvent from the composition to form a film.~~

2-10. (Canceled)

11. (New) A method of forming a film on a substrate, comprising:

discharging a liquid material from a nozzle of a head to the substrate to form a film on the substrate, the liquid material including a solvent and a solute, the solvent including a heterocyclic compound, the heterocyclic compound having a furan skeleton, and a boiling point of the heterocyclic compound being greater than 170 degrees centigrade.

12. (New) The method according to claim 11, the solvent including 2,3-dihydrobenzofuran.

13. (New) The method according to claim 11, the solvent including a benzene derivative.

14. (New) The method according to claim 11, a vapor pressure of the solvent at room temperature being less than 10 mmHg and greater than 0.10 mmHg.

15. (New) The method according to claim 11, the solute including a semiconductor material.

16. (New) The method according to claim 11, the solute including a conductive material.

17. (New) The method according to claim 11, the substrate having an electrode formed thereon, the discharging step comprising discharging the liquid material from the nozzle of the head to the electrode to form the film on the electrode.

18. (New) A method of forming an electro-optical device using the method of forming a film on a substrate according to claim 11.